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Part Number:

0739434200

Status:

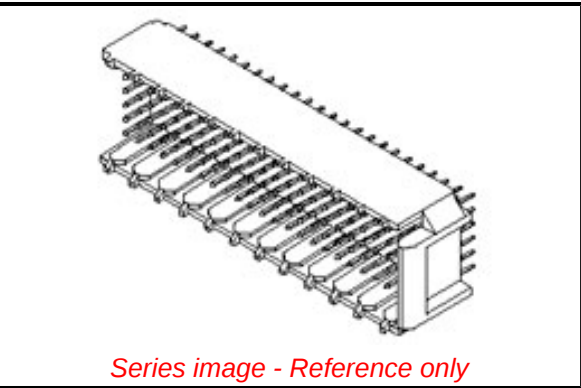
Active

Overview:

HDM® Backplane Connector System

Description:

HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Closed End, 72 Circuits



Documents:

3D Model

Packaging Specification PK-70873-0818 (PDF)

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification		
CSA		LR19980
UL		E29179
General		
Product Family		Backplane Connectors
Series		73943
Application		Backplane
Comments		Solder Tail
Component Type		PCB Header
Overview		HDM® Backplane Connector System
Product Name		HDM®
UPC		800754842327
Physical		
Circuits (Loaded)		72
Circuits (maximum)		72
Color - Resin		Black, Natural
Durability (mating cycles max)		250
First Mate / Last Break		No
Flammability		94V-0
Guide to Mating Part		No
Keying to Mating Part		None
Material - Metal		Phosphor Bronze
Material - Plating Mating		Gold
Material - Plating Termination		Tin
Material - Resin		High Temperature Thermoplastic
Net Weight		3.554/g
Number of Columns		12
Number of Pairs		Open Pin Field
Number of Rows		6
Orientation		Vertical
PC Tail Length		3.00mm
PCB Locator		No
PCB Retention		None
PCB Thickness - Recommended		2.50mm
Packaging Type		Tube
Pitch - Mating Interface		2.00mm
Pitch - Termination Interface		2.00mm
Plating min - Mating		0.762µm
Plating min - Termination		2.540µm
Stackable		Yes
Surface Mount Compatible (SMC)		Yes
Temperature Range - Operating		-55°C to +105°C
Termination Interface: Style		Through Hole

Electrical

EU ELV

Not Relevant

EU RoHS

China RoHS

Compliant

REACH SVHC

Not Contained Per -

ED/21/2016 (20 June

2016)

Halogen-Free

Status

Low-Halogen

Need more information on product

environmental compliance?

Email productcompliance@molex.com

Please visit the [Contact Us](#) section for any

non-product compliance questions.

China ROHS

Green Image

ELV

Not Relevant

RoHS Phthalates

Not Contained

Search Parts in this Series

73943 Series

Mates With

73632 HDM+® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Sales Drawing	SD-73943-001

Note: HDM, HDM+, VHDM, VHDM-HSD and GbX are trademarks or registered trademarks of Amphenol TCS.

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